

Amendment to the Claims

1-11. (Cancelled)

12. (Previously Presented) A method for removing semiconductor chip in which one out of a plurality of semiconductor chips formed from a diced semiconductor wafer is removed from a pressure-sensitive adhesive sheet, which holds the semiconductor chips by adhering thereto, so that the semiconductor chip is extracted from the adhesive sheet, the method comprising:

bringing a plurality of protruding portions on a first contact surface of a removing member into contact with a bottom surface of the semiconductor chip through the adhesive sheet at a region on a bottom surface side of the adhesive sheet while sucking and holding a vicinity of the bottom surface-side region of the adhesive sheet corresponding to an adhesion region of the semiconductor chip by a second contact surface of a holding portion located around the first contact surface;

sucking the adhesive sheet in between the respective protruding portions so as to partially remove the adhesive sheet in the adhesion region from the semiconductor chip at suction positions; and

moving respective contact positions with the protruding portions to the suction positions on the bottom surface-side region of the adhesive sheet by moving the removing member along the bottom surface of the semiconductor chip relative to the holding portion, in a condition in which the first contact surface is located at an almost same height of the second contact surface, so that a region of the partial removal in the adhesion region is made to expand.

13. **(Currently Amended)** The method for removing semiconductor chip as defined in Claim 12, wherein a force for sucking and holding~~to suck and hold~~ the vicinity of the bottom surface-region of the adhesive sheet corresponding to the adhesion region is set to be larger than a force for sucking~~to suck~~ the adhesive sheet in between the respective protruding portions.

14. **(Previously Presented)** The method for removing semiconductor chip as defined in Claim 12, wherein the movement of the removing member is a reciprocal movement of the removing member in a specified direction along the bottom surface of the semiconductor chip.

15. **(Currently Amended)** The method for removing semiconductor chip as defined in Claim 14, wherein an amplitude of the~~in the~~ reciprocal movement of the removing member is larger than a formation interval of the respective protruding portions.

16. **(Previously Presented)** The method for removing semiconductor chip as defined in Claim 12, wherein the movement of the removing member is a rotating movement of the removing member around a direction almost perpendicular to the bottom surface of the semiconductor chip.

17. **(Cancelled)**

18. **(Previously Presented)** The method for removing semiconductor chip as defined in Claim 12, wherein the movement of the removing member is a reciprocal movement of the removing

member in a specified direction with a specified amplitude along the bottom surface of the semiconductor chip.

19. (Cancelled)

20. (New) The method for removing semiconductor chip as defined in Claim 13, wherein the force for sucking and holding the vicinity of the bottom surface-region of the adhesive sheet corresponding to the adhesion region is controlled by a first valve, and the force for sucking the adhesive sheet in between the respective protruding portions is controlled by a second valve.